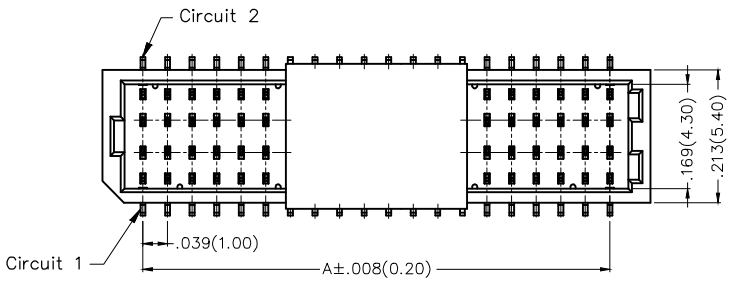
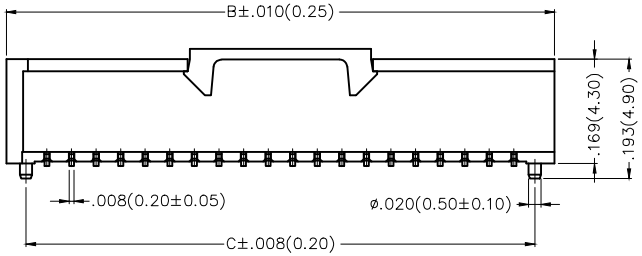
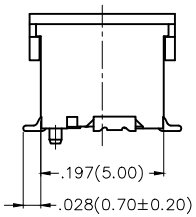
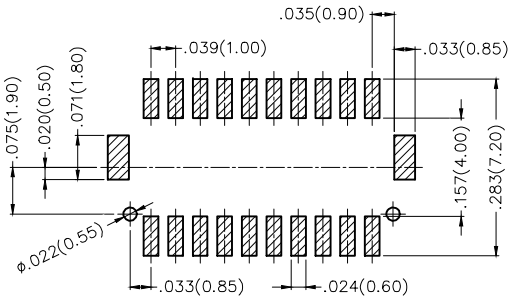
REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD









Recommended P.C.Board Layout

SPECIFICATIONS

Electrical
- Current Rating: 1.0A AC(rms)/DC
- Voltage Rating: 50V AC(rms)/DC
- Contact Resistance: 20 mΩ Max
- Insulation Resistance: 100 MΩ MIN
- Withstanding Voltage: 1000V AC r.m.s
- Temperature Range–Operating: –25℃~+85℃

Material and Plating
- Housing: PA6T UL94V–0
- Pin: Copper Alloy/ Gold Plated
- Solder Tab: Copper Alloy

Circuits (n)	Part No.	Dimensions(in/mm)		
		A	B	C
10	FWF10007–D10S14W5M	.157(4.00)	.287(7.30)	.224(5.70)
12	FWF10007–D12S14W5M	.197(5.00)	.327(8.30)	.264(6.70)
16	FWF10007–D16S14W5M	.276(7.00)	.406(10.30)	.343(8.70)
20	FWF10007–D20S14W5M	.354(9.00)	.484(12.30)	.421(10.70)
30	FWF10007–D30S14W5M	.551(14.00)	.681(17.30)	.618(15.70)
40	FWF10007–D40S14W5M	.748(19.00)	.878(22.30)	.815(20.70)
50	FWF10007–D50S14W5M	.945(24.00)	1.075(27.30)	1.012(25.70)

Ordering Information

FWF	100	07	—	D	XX	S	1	4	W5	M
1	2	3		4	5	6	7	8	9	10

1	Category	2	Series Number	3	Distinction No.	4	Row Option	5	Circuits		
	FWF–Wafer		100–Pitch1.00mm		07		D–Double Row		XX		
6	Entry Angle	7	Plating	8	Material–Resin	9	Color–Resin	10	Packaging		
	S–180° Vertical		1–Gold Plated		4–PA6T		W5–White		M–Reel		

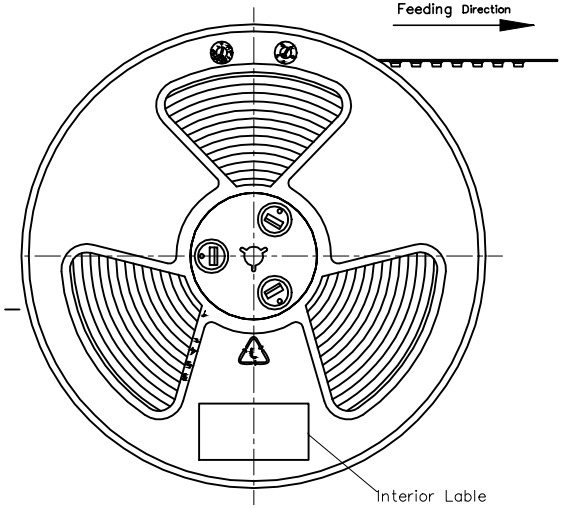
THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 18/JUN/13	PART NO. FWF10007–DXXS14W5M	ITEM NO. FWF10007
DESIGN UNITS Inch (metric)	X.±.012(0.30)	X.°±5°	CHECKED BY CHERRY	DATE 18/JUN/13	TITLE Wire to Board (Wafer) Pitch 1.0mm 180° Vertical (SMT)	REV 0 / SHEET NO. 1/2
	X.X±.008(0.20)	.X°±2°				
	X.XX±.006(0.15)	.XX°±1°				
SCALE 5:1 / SIZE A4	X.XXX±.004(0.10)	.XXX°±0.5°	DRAWN BY KATE	DATE 18/JUN/13	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	

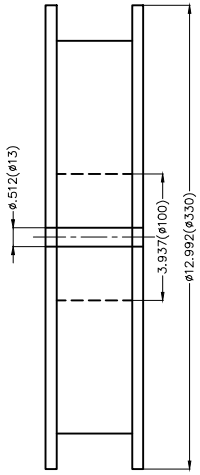
TXGA Leader Of Industry

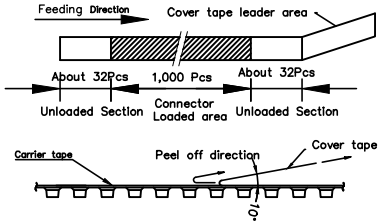
REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD

Note:

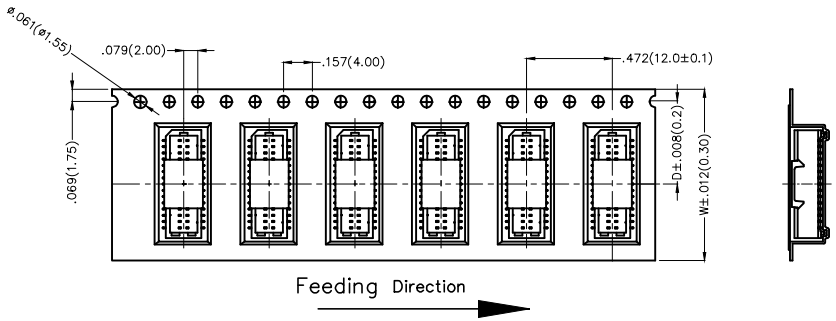
1. 10 sprocket hole cumulative tolerance±0.2
2. Carrier camber is within 1.0mm in 250mm
3. Materlat: White Conductive polystyrene Alloy 100% recyclable
4. All dimensions meet EIA-481-3 requirements
5. Peel off force of cover tape&carrier tape: 20g~130g(0.2N~1.3N)
6. Component load per 13" reel: 1,000 pcs

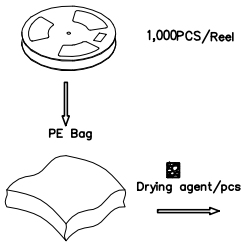


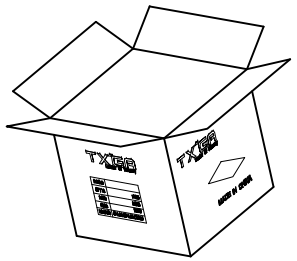




Circuits (n)	Dimensions(in/mm)	
	D	W
10	.453(11.50)	.945(24.00)
12	.453(11.50)	.945(24.00)
16	.453(11.50)	.945(24.00)
20	.453(11.50)	.945(24.00)
30	.453(11.50)	.945(24.00)
40	.798(20.20)	1.732(44.00)
50	.798(20.20)	1.732(44.00)







THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY	DATE	PART NO. FWF10007-DXXS14W5M / ITEM NO. FWF10007
	X.±.012(0.30)	X.°±5°	FRANK	28/JUN/13	TXGA Leader Of Industry
DESIGN UNITS Inch (metric)	X.X±.008(0.20)	.X°±2°	CHECKED BY JACOB	DATE 28/JUN/13	TITLE Wire to Board (Wafer) Pitch 1.0mm 180° Vertical (SMT)
SCALE 5:1 / SIZE A4	X.XX±.006(0.15)	.XX°±1°	DRAWN BY CHERRY	DATE 28/JUN/13	REV 0 / SHEET NO. 2/2
	X.XXX±.004(0.10)	.XXX°±0.5°			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION